



SFF-TA-1006

Specification for

Enterprise and Datacenter 1U Short ~~SSD-Device~~ Form Factor (E1.S)

Rev 1.4.2 ~~March 27, 2020~~ June 29, 2021

SECRETARIAT: SFF TA TWG

This specification is made available for public review at <https://www.snia.org/sff/specifications>. Comments may be submitted at <https://www.snia.org/feedback>. Comments received will be considered for inclusion in future revisions of this specification.

Field Code Changed
Field Code Changed

The description of the form factor in this specification does not assure that the specific component is available from suppliers. If such a form factor is supplied, it should comply with this specification to achieve interoperability between suppliers.

ABSTRACT: This specification defines the mechanical attributes of a 1U short form factor for a ~~solid-state drive device with multiple thicknesses that will fit in vertically in standard 1U rack mounted host systems. that fits vertically in host systems designed to fit in one or multiple units of the standard 1U rack mount height.~~

This specification provides a common reference for host systems manufacturers, host system integrators, and device suppliers. This specification originates from Enterprise and Datacenter SSD Form Factor Working Group (EDSFF). ~~Based on non-SSD devices also using EDSFF and agreement from the EDSFF Working Group, the SFF TA TWG agreed changing EDSFF to Enterprise and Datacenter Standard Form Factor.~~

The description of the device in this specification does not assure that the specific component is actually available from device suppliers. If such a device is supplied it shall comply with this specification to achieve interoperability between device suppliers.

POINTS OF CONTACT:

Anthony Constantine
Intel Corporation
2111 NE 25th Ave
MS JF5-270

Jonathan Hinkle
Lenovo
7001 Development Drive
Morrisville, NC 27560,

Chairman SFF TA TWG
Email: SFF-Chair@snia.org

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1 Hillsboro, OR 97124
2 Ph: 971 215 1128
3 Email: anthony.m.constantine@intel.com
4

Ph: 919 257 6211
Email: jhinkle@lenovo.com

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Foreword

The development work on this specification was done by the SNIA SFF TWG, an industry group. Since its formation as the SFF Committee in August 1990, the membership has included a mix of companies which are leaders across the industry.

For those who wish to participate in the activities of the SFF TWG, the signup for membership can be found at <https://www.snia.org/sff/join>.

Revision History

- Rev 1.0** *January 16, 2018:*
-Initial release with editorial fixes to TOC and Fig 4-1 diagram
- Rev 1.1** *June 1, 2018:*
-Updated IP section and foreword per current policy.
-Corrected ASME reference in 2.3 for consistency.
-Corrected dimension F1 in Table 4-1.
-Corrected Figure 4-2 to remove E dimension and changed the radius of the notches in Detail and B.
-Further updates to TOC
- Rev 1.2** *April 12, 2019*
-Converted to the new SFF document template
-Added new name (E1.S).
-Clarified abstract.
-Section 3.3: Added definition for enclosure and modified definition of 1U.
-Section 5: Clarified power is a recommendation and added recommended power for optional heat spreader and optional enclosures.
-Section 5.1: Added clarification to bounding volume, surface dimensions, and rounding.
-Table 5-1: Modified Measurement C2 to align with SFF-TA-1002.
-Table 5-1: Modified Measurements D3 and D4.
-Table 5-1: Fixed the comment for Measurement F6.
-Section 5.4, 5.5: Added. This adds optional symmetric and asymmetric enclosure dimensions.
-Section 7: Added. This is an informative section on system thermal design guidelines.
- Rev 1.3** *July 17, 2019*
-Section 5.1: Added statement to clarify that PCB dimensions are not required but highly recommended for enclosures specified in sections 5.4 and 5.5.
-Section 5.1 changed added wording for PCB in enclosures
-Figure 5.1: Added new dimension D5
-Figure 5.1: Added label for LED facing side
-Table 5.1: Clarified measurement for D1, D2 is to LED center position
-Table 5-1: Made E1-E7 BASIC to match the drawing
-Table 5.1: Added comment to drawing on mounting hole dependency to C2
-Section 5.4, 5.5, 6: Added x8 Card Edge along with Dimension B10 (Enclosure to x8 Datum F)
-Section 5.4, 5.5: Added Measurement C8 (Datum Y to Datum T), B11 (Datum W to LED center)
-Section 5.5: Added note to clarify Section 5.5 dimensions are equivalent to section 5.4
-Figure 5-3, 5-4: Add label to primary and secondary side
-Figure 5-3, 5-4: Change drawing ordering
-Figure 5-3, 5-4, Table 5-3: Added dimensions D6, D7, D8, E16
-Table 5-3: Fixed an error in value of B8.
-Table 5-4: Deleted dimensions B8 and B9. Redundant
- Rev 1.4** *March 27, 2020*
- Added 15mm asymmetric thickness to section 5.5, corresponding thermal entry in Table 7.1 and descriptions in sections 5.1 and 7.1.
- Rev 1.4.1** *April 30, 2021*
-Changed SSD to device and abstract edit to reflect EDSFF name change.

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- Section 5: Clarification on power and only PCB card edge is exposed outside the enclosure area.
- Section 5: Removal of default tolerance and added tolerances to Table 5-2.
- Section 5: Datum name change from "Y" to "G" to align with SFF-TA-1002 Datum.
- Section 5: Removal of Power references apart from section 5.1 recommendations.
- Section 5.4, 5.5: Clarification that both 1C and 2C card edges are allowed.
- Section 5.4, 5.5: Removed measurement E16 (REF dimension) and moved C8 to a different view.
- Section 5.4, 5.5: Note added for recommended ground contact.
- Section 7: Deleted informative thermal guidance. Replaced with power and thermal requirements.

Rev 1.4.2

June 29, 2021

- Section 3.1: Change to definition of Restricted
- Section 5: Moved the power references in section 5.1 to an informative table.
- Section 5.1: Moved statements on mounting holes, defined hatch, and labels to Section 5.2
- Table 5-1: Changed C2 note to cover 7.5 mm instead of 7 mm.
- Table 5-1: Removed x, y references to mounting hole measurements.
- Table 5-1: Removed dimensions in comments for the cutouts.
- Table 5-2: Removed heat spreader option and x, y references in the comments.
- Section 5.1: Added statement allowing security labels to be placed anywhere on the enclosure.
- Figure 5-4, : Added Phi to E14
- Section 5.4, 5.5: Changed note 1 wording.
- Section 5.4, 5.5: Added note on security label being allowed in label keep out region.
- Section 5.4, 5.5: Changed PCB expose from shall to should. Intent to make shall in future revision.
- Table 7-1: Added an entry for bare PCB vs. enclosure-based device.

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Contents

1		
2	1. Scope	776
3	1.1 Application Specific Criteria	776
4	2. References and Conventions	776
5	2.1 Industry Documents	776
6	2.2 Sources	776
7	2.3 Conventions	887
8	3. Keywords, Acronyms, and Definitions	998
9	3.1 Keywords	998
10	3.2 Acronyms and Abbreviations	998
11	3.3 Definitions	10109
12	4. General Description	111110
13	4.1 Configuration Overview/Descriptions	111110
14	5. Mechanical Specification	121211
15	5.1 Overview	121211
16	5.2 Physical Definition: 1U Short Form Factor	131311
17	5.2.1 1U Short Form Factor	141412
18	5.3 Physical Definition: 1U Short Form Factor with Optional Heat Spreader	151513
19	5.3.1 1U Short Form Factor with Optional Heat Spreader	151513
20	5.4 Physical Definition: 1U Short Form Factor with Optional Symmetric Enclosure	161614
21	5.4.1 1U Short Form Factor with Optional Symmetric Enclosure	181815
22	5.5 Physical Definition: 1U Short Form Factor with Optional Asymmetric Enclosure	191916
23	5.5.1 1U Short Form Factor with Optional Asymmetric Enclosure	222217
24	6. Informative: SFF-TA-1002 edge (plug) Mechanical drawing	232318
25	6.1 Overview	232318
26	7. E1.S Power/Thermal Requirements	242419
27	7.1 Power	242419
28	7.2 Thermals	242419
29		
30		
31	Figures	
32	Figure 4-1. Example system implementations of 1U short form factor.	111110
33	Figure 5-1. 5.9mm Thick 1U Short Form Factor drawing	Error! Bookmark not defined.
34	Error! Bookmark not defined.	
35	Figure 5-2. 1U Short Form Factor drawing with heat spreader option	151513
36	Figure 5-3. 1U Short Form Factor drawing with Optional Symmetric Enclosure	171714
37	Figure 5-4. 1U Short Form Factor drawing with Optional Asymmetric Enclosure	212116
38	Figure 6-1. 1C (x4) Mating Card Dimensions	232318
39	Figure 6-2. 2C (x8) Mating Card Dimensions	232318
40		
41		
42	Tables	
43	Table 5-1. 1U Short Form Factor Dimensions	141412
44	Table 5-2. 1U Short Form Factor – Optional Heat Spreader Dimensions	151513
45	Table 5-3. 1U Short Form Factor – Optional Symmetric Enclosure Dimensions	181815
46	Table 5-4. 1U Short Form Factor – Optional Asymmetric Enclosure Dimensions	222217
47	Table 7-1. Power Requirements for a 1U short (E1.S) system implementation	242419
48		
49		

1. Scope

This specification defines the mechanical attributes of a new form factor for a solid-state drive device that will fit in 1U rack mounted host systems designed to support this form factor.

1.1 Application Specific Criteria

This 1U short form factor provides external dimensions, card edge placement, grounded mechanical mounting hole locations and LED placement to assist host system manufacturers in integration of this form factor.

The environment for the 1U short form factor is an enclosure connecting one or more drives-devices in a restricted dedicated packaging environment.

2. References and Conventions

2.1 Industry Documents

The following documents are relevant to this specification:

- ASME Y14.5-2009 Dimensioning and Tolerancing Published by ASME at <https://www.asme.org>
- SNIA SFF-TA-1002 Protocol Agnostic Multi-Lane High Speed Connector specification available at <https://www.snia.org>
- SNIA SFF-TA-1009 Enterprise and Datacenter Standard Form Factor Pin and Signal Specification available at <https://www.snia.org>
- SNIA SFF-TA-1023 Thermal Characterization Specification for EDSFF Devices available at <https://www.snia.org>

2.2 Sources

The complete list of SFF documents which have been published, are currently being worked on, or that have been expired by the SFF Committee can be found at <https://www.snia.org/sff/specifications>. Suggestions for improvement of this specification will be welcome, they should be submitted to <https://www.snia.org/feedback>.

Copies of ASME standards may be obtained from the American Society of Mechanical Engineers (<https://www.asme.org>).

2.3 Conventions

The following conventions are used throughout this document:

DEFINITIONS

Certain words and terms used in this standard have a specific meaning beyond the normal English meaning. These words and terms are defined either in the definitions or in the text where they first appear.

ORDER OF PRECEDENCE

If a conflict arises between text, tables, or figures, the order of precedence to resolve the conflicts is text; then tables; and finally figures. Not all tables or figures are fully described in the text. Tables show data format and values.

DIMENSIONING CONVENTIONS

The dimensioning conventions are described in ASME-Y14.5, Geometric Dimensioning and Tolerancing. All dimensions are in millimeters, which are the controlling dimensional units (if inches are supplied, they are for guidance only).

NUMBERING CONVENTIONS

The ISO convention of numbering is used (i.e., the thousands and higher multiples are separated by a space and a period is used as the decimal point). This is equivalent to the English/American convention of a comma and a period.

American	French	ISO
0.6	0,6	0.6
1,000	1 000	1 000
1,323,462.9	1 323 462,9	1 323 462.9

3. Keywords, Acronyms, and Definitions

For the purposes of this document, the following keywords, acronyms, and definitions apply.

3.1 Keywords

May: Indicates flexibility of choice with no implied preference.

May/or may not: Indicates flexibility of choice with no implied preference.

Obsolete: Indicates that an item was defined in prior specifications but has been removed from this specification.

Optional: Describes features which are not required by the SFF specification. However, if any feature defined by the SFF specification is implemented, it shall be done in the same way as defined by the specification. Describing a feature as optional in the text is done to assist the reader.

Prohibited: Describes a feature, function, or coded value that is defined in a referenced specification to which this SFF specification makes a reference, where the use of said feature, function, or coded value is not allowed for implementations of this specification.

Reserved: Defines the signal on a connector contact [when] its actual function is set aside for future standardization. It is not available for vendor specific use. Where this term is used for bits, bytes, fields, and code values; the bits, bytes, fields, and code values are set aside for future standardization. The default value shall be zero. The originator is required to define a Reserved field or bit as zero, but the receiver should not check Reserved fields or bits for zero.

Restricted: Refers to features, bits, bytes, words, and fields that are set aside for other standardization purposes. If the context of the specification applies the restricted designation, then the restricted bit, byte, word, or field shall be treated as ~~a value whose definition is not in scope of this document, and is not interpreted by this specification, a reserved bit, byte, word, or field (e.g., a restricted byte uses the same value as defined for a reserved byte).~~

Shall: Indicates a mandatory requirement. Designers are required to implement all such mandatory requirements to ensure interoperability with other products that conform to this specification.

Should: Indicates flexibility of choice with a strongly preferred alternative.

Vendor specific: Indicates something (e.g., a bit, field, code value) that is not defined by this specification. Specification of the referenced item is determined by the manufacturer and may be used differently in various implementations.

3.2 Acronyms and Abbreviations

EDSFF: Enterprise and Datacenter Standard Form Factor

NVM: Non-Volatile Memory

SSD: Solid State Drive

1 **3.3 Definitions**

2 **1U:** 1 Standard Unit or Rack Unit 44.45 mm (1.75 inches).

3
4 **Card:** Refers to the device plugged into a connector

5
6 **Device:** Refers to the interface ~~slavetarget~~

7
8 **Enclosure:** The housing that protects the internal components and acts as a heat sink.

9
10 **Host:** Refers to the interface source or ~~master-initiator~~

11
12 **Thickness:** Form factor dimension including PCB thickness, z-height of all components plus mechanicals.

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4. General Description

4.1 Configuration Overview/Descriptions

The application environment for the 1U short form factor is a cabinet or enclosure connecting to one or more add-in cards. 1U refers to 1 standard unit of an IT equipment rack and the IT enclosures that fit in this space. The SSD-device form factor is intended for use in enclosures that fit within that given space. The primary usage is for datacenter server and storage systems that require high capacity and performance highly scalable in 1U. The device connects electrically to the system through a card edge connector as defined in SFF-TA-1002. There are multiple thicknesses of the 1U short form factor depending on the max power rating. The definition of mounting holes and component placement area allows for attachment of mechanicals to adapt among different enclosure chassis, such as rails and latching. The form factor is designed not to require a fully enclosed case, but outer dimensions of a case version are included for compatibility if one is desired. [Figure 4-14-1](#) ~~Figure 4-1~~ represents an example of a system implementation using the 1U short form factor.

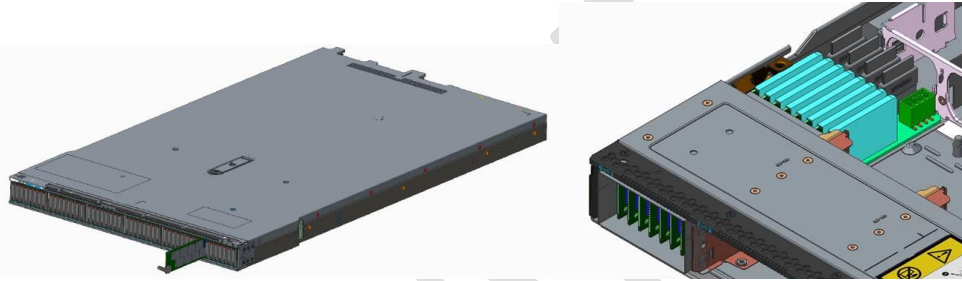


Figure 4-14-1. Example systems showing implementations of 1U short form factor.

5. Mechanical Specification

5.1 Overview

This section specifies the dimensions for the 1U short form factor. There are multiple thicknesses specified:

- A 5.9 mm thick PCB form factor ~~with a recommended power rating of 12W~~
- ~~The form factor~~ An 8.01 mm thick PCB with an optional heat spreader ~~and a recommended power rating of 16W~~
- The form factor with an optional 9.5 mm symmetrical enclosure ~~and a recommended power rating of 20W~~
- The form factor with an optional 15 mm asymmetric enclosure
- ~~The form factor with an optional 15 mm or 25 mm asymmetric enclosure and a recommended power rating of 25W~~

~~All specified mounting holes shall be grounded and mechanical attachment should not exceed radius of defined copper pads. The defined hatched area is component placement area. Unless specified, any labels must be in component placement or optional heat spreader area. No part of the host chassis/guide rails of a host enclosure or parts connected to the mounting holes (e.g., a latch) should encroach into any part of the bounding volume of the device form factor dimensions and tolerances as specified in this standard when the device is inserted into the host enclosure.~~

Unless specified, the default tolerance is +/- 0.15mm. All dimensions provided in mm.

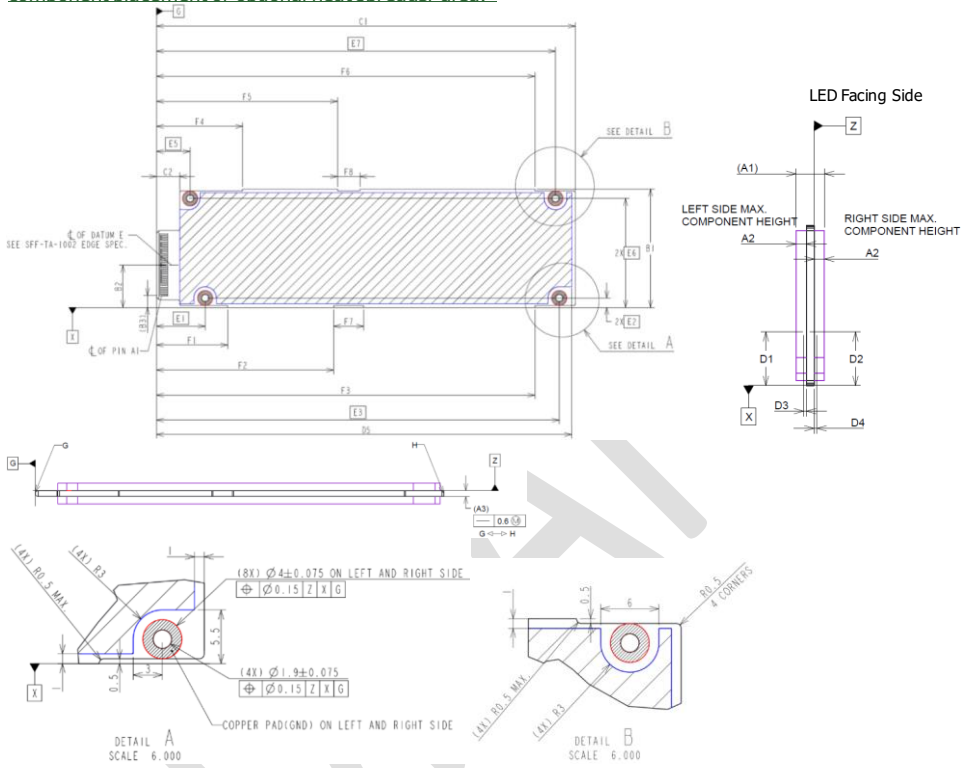
For the label placement and fin area, dimensions for a surface apply to a single point minimum. If a surface is not flat, the dimension applies to the highest raised location on that surface. Except for the card edge connector, each defined edge may have rounding.

The form factors specified in Section 5.2 and Section 5.3 may be used within the enclosures specified in Section 5.4 and 5.5, but is not required ~~however the PCB component area shall not be outside of the enclosure area~~. The PCB with 2C (x8) card edge is not required to meet Section 5.2.

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5.2 Physical Definition: 1U Short Form Factor

All specified mounting holes shall be grounded and mechanical attachment should not exceed radius of defined copper pads. The defined hatched area is component placement area. Unless specified, any labels must be in component placement or optional heat spreader area.



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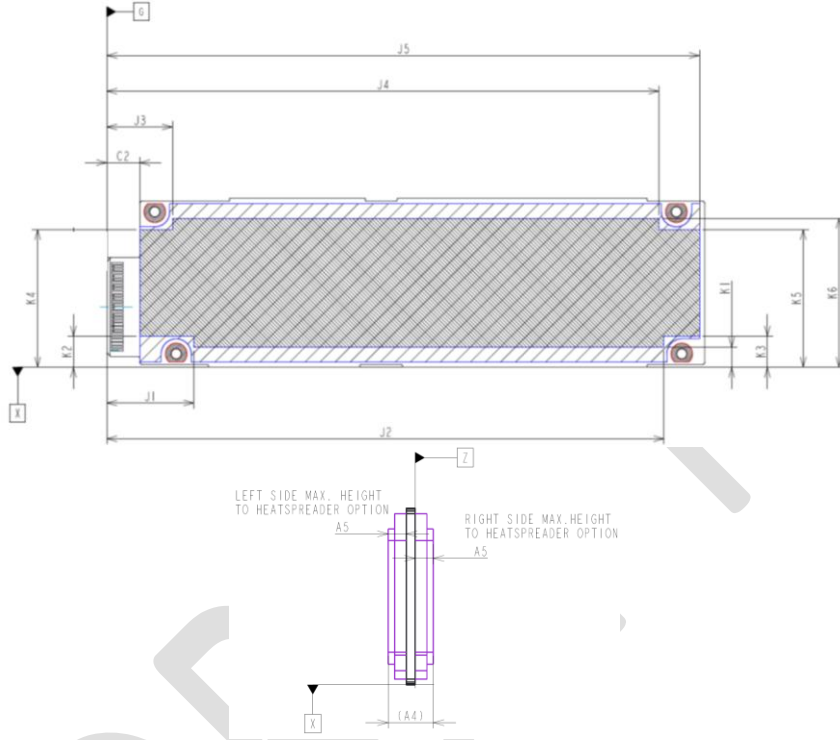
Figure 5-1. 5.9mm Thick 1U Short Form Factor drawing (12W)

5.2.1 1U Short Form Factor

Table 5-15-1. 1U Short Form Factor Dimensions

Dimensions	Millimeters	Tolerance	Comment
A1	5.9	MAX	Maximum drive device thickness (reference)
A2	2.10	MAX	Maximum component height
A3	1.57	0.13	PCB Card Edge thickness (ref: see SFF-TA-1002)
B1	31.5	0.2	Drive Device height with defined cutouts
B2	11.23	0.15	Card Bottom Edge to centerline of Datum E
B3	3.21	0.15	Center of Connector Pin A1 location from PCB (reference)
C1	111.49	0.15	Add in card Length
C2	6	Min	Card edge length. Note if dimension is greater than 7.5 mm, mounting hole 3 is allowed to be a half-moon
D1	10.6	0.15	Power and activity (Green) LED center position
D2	10.6	0.15	Attention or error (Amber) LED center position
D3	0.5	0.2	Power and activity (Green) LED center position
D4	0.5	0.2	Attention or error (Amber) LED center position
D5	110.49	0.45	LED edge closest to latch area
E1	12.95	BASIC	Mounting hole 1 x-position
E2	2.5	BASIC	Mounting hole 1 y- and 2y-positions
E3	107.19	BASIC	Mounting hole 2 x-position
E5	8.95	BASIC	Mounting hole 3 x-position
E6	29	BASIC	Mounting hole 3 y- and 4y-positions
E7	106.19	BASIC	Mounting hole 4 x-position
F1	18.95	0.15	Cutout 1 --12.8x0.5
F2	47.15	0.15	Cutout 2 --8x0.5
F3	100.69	0.15	Cutout 3 --10.8x0.5
F4	22.95	0.15	Cutout 4 --16.8x0.5
F5	48.15	0.15	Cutout 5 --6x0.5
F6	100.69	0.15	Cutout 6 --10.8x0.5
F7	8	0.15	Width of cutout 2
F8	6	0.15	Width of cutout 5

1 **5.3 Physical Definition: 1U Short Form Factor with Optional Heat Spreader**



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4 **Figure 5-25-2. 1U Short Form Factor drawing with heat spreader option (16W)**

5 **5.3.1 1U Short Form Factor with Optional Heat Spreader**

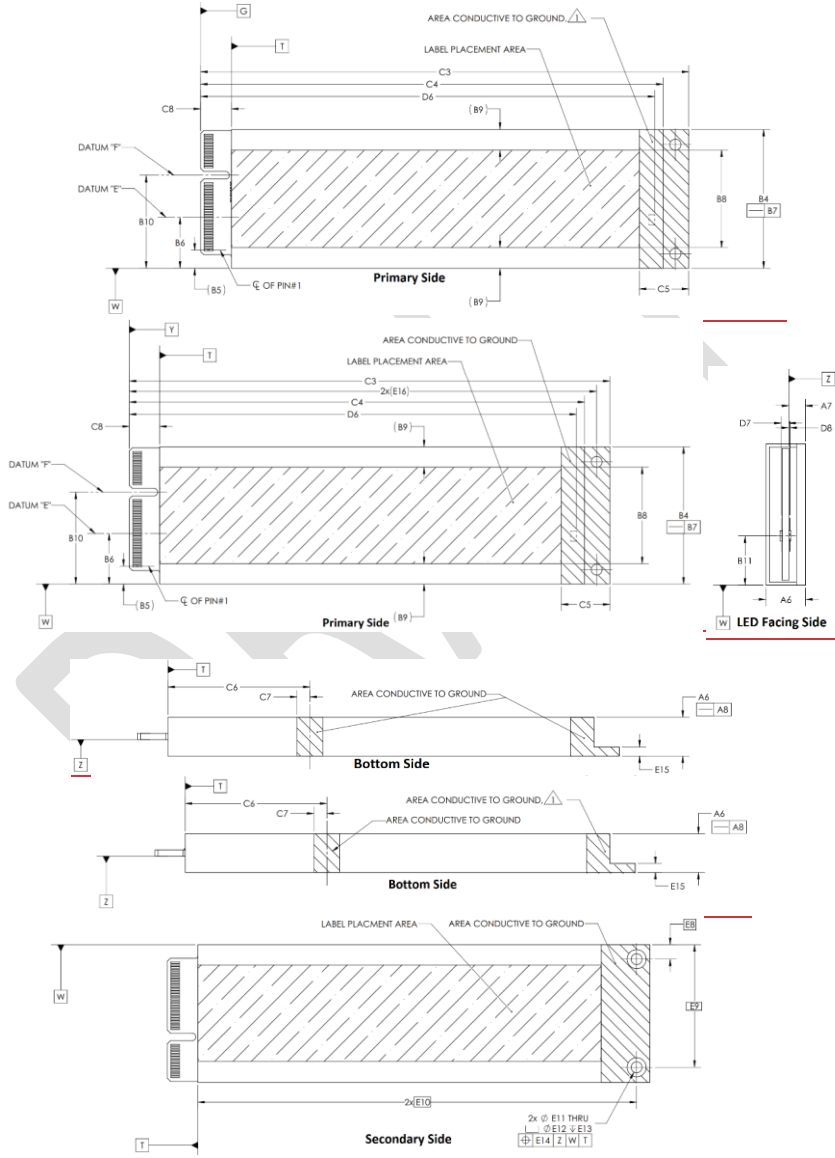
6 **Table 5-25-2. 1U Short Form Factor – Optional Heat Spreader Dimensions**

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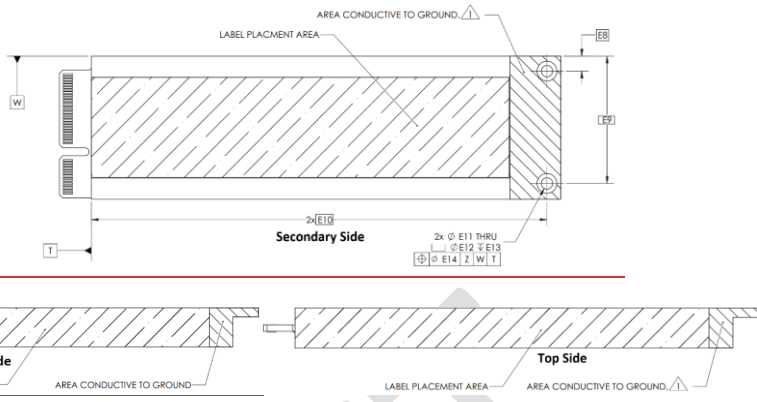
Dimensions	Millimeters	Tolerance	Comment
A4	8.01	0.15	Drive Device thickness including heat spreader (reference)
A5	3.22	0.25	PCB to outer thickness for heat spreader option
J1	16.25	0.15	Heat spreader option 1 dimension x position
J2	103.89	0.15	Heat spreader dimension Heatspreader option 2 x position
J3	12.25	0.15	Heat spreader dimension Heatspreader option 3 x position
J4	102.89	0.15	Heat spreader dimension Heatspreader option 4 x position
J5	110.49	0.15	Heat spreader dimension Heatspreader option 5 x position
K1	3.7	0.15	Heat spreader dimension Heatspreader option 1 y position
K2	5.8	0.15	Heat spreader dimension Heatspreader option 2 y position
K3	5.8	0.15	Heat spreader dimension Heatspreader option 3 y position
K4	25.7	0.15	Heat spreader dimension Heatspreader option 4 y position
K5	25.7	0.15	Heat spreader option 5 y position dimension
K6	27.8	0.15	Heat spreader dimension option 6 y position

5.4 Physical Definition: 1U Short Form Factor with Optional Symmetric Enclosure

The PCB excluding the card edge should not extend past the defined enclosure area. The device defined in the following section supports either the 1C or 2C card edge as defined in SFF-TA-1002. The area conductive to ground may be larger than what is documented. Labels shall be placed in the label placement area. Security labels are permitted on any surface of the enclosure.



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Notes:

- 1. Host should make grounding contact to at least 1 of these surfaces on the LED facing side.

Figure 5-35-3. 1U Short Form Factor drawing with Optional Symmetric Enclosure (20W)

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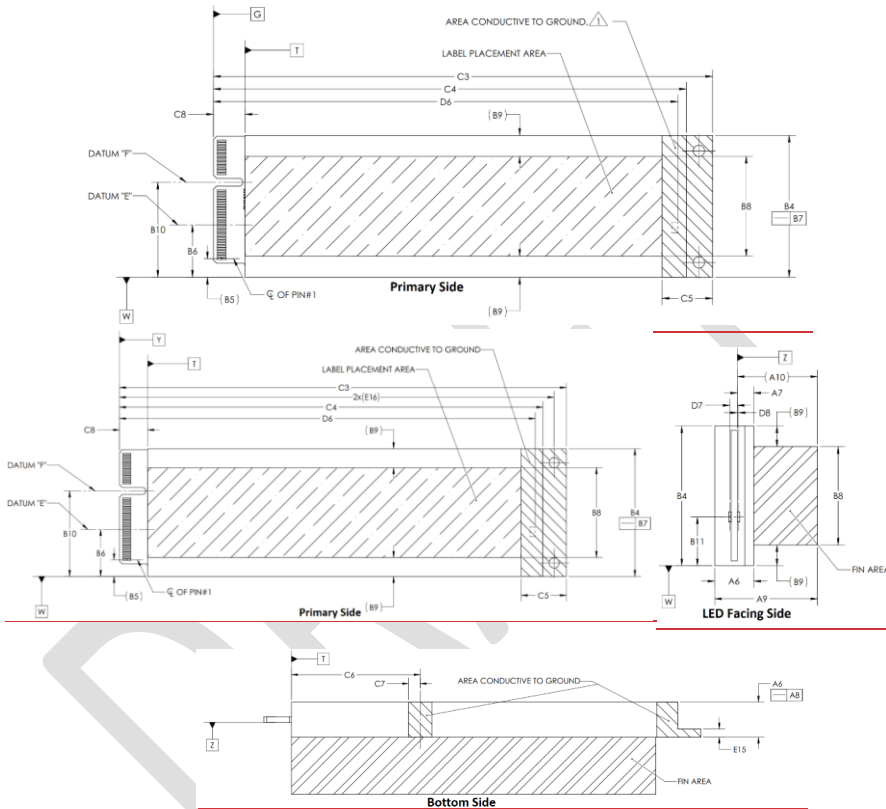
5.4.1 1U Short Form Factor with Optional Symmetric Enclosure

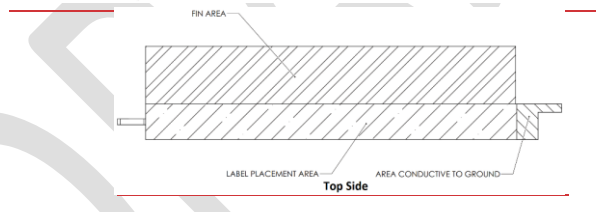
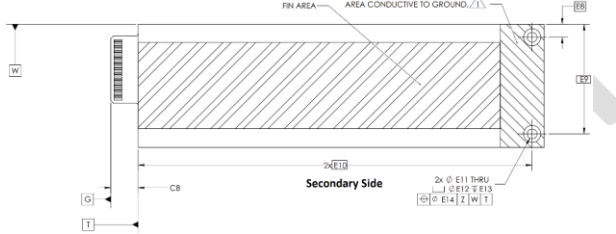
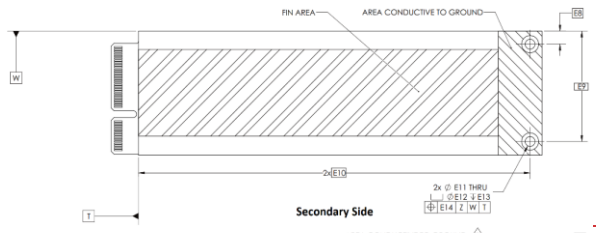
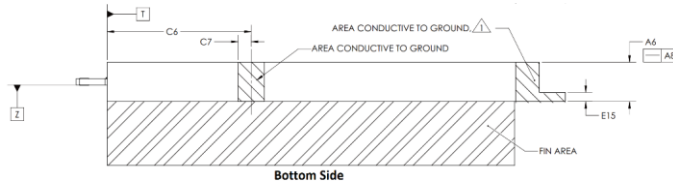
Table 5-35-3. 1U Short Form Factor – Optional Symmetric Enclosure Dimensions

Dimensions	Millimeters	Tolerance	Comment
A6	9.5	0.35	Device Thickness including enclosure
A7	3.96	0.15	PCB at LED and card edge connector to outer thickness
A8	0.4	MAX	Straightness
B4	33.75	0.25	Device width
B5	4.4	REF	Center - Connector Pin A1 location from Datum X
B6	12.415	0.35	Control dimension for x4 card edge; TA-1002 DATUM "E"
B7	0.4	MAX	Straightness
B8	23.75	0.25	Label/Fin placement region
B9	5	REF	Host alignment structure region (reference)
B10	22.605	0.35	Control dimension for x8 card edge; TA-1002 DATUM "F"
B11	11.79	0.35	Datum "W" to LED center position
C3	118.75	0.55	Device length
C4	112.5	+0.15/-0.95	Datum "G" to latch area keep out zone
C5	12	MIN	Minimum Conductive area length
C6	35	0.15	Bottom conductive area 1 x position
C7	3.2	MIN	Bottom conductive area length
C8	7.5	0.25	Datum "G" to Datum "T" (edge of enclosure)
D6	110.49	0.45	LED edge closest to latch area
D7	2.07	0.48	Green LED center position
D8	0.5	0.35	Amber LED center position
E8	3.55	BASIC	Mounting Hole 1 y-g position
E9	30.05	BASIC	Mounting Hole 2 y-g position
E10	108	BASIC	Mounting Hole 1 x and 2 x position
E11	2.7	0.15	Mounting Thru Hole Diameter
E12	4.7	0.15	Mounting Counterbore Diameter
E13	1.2	0.1	Mounting Counterbore Depth
E14	0.25	MAX	Position Tolerance
E15	2.2	0.15	Latch mounting area thickness
E16	115.5	REF	Card Edge to Mounting Hole 1 x and 2 x Position

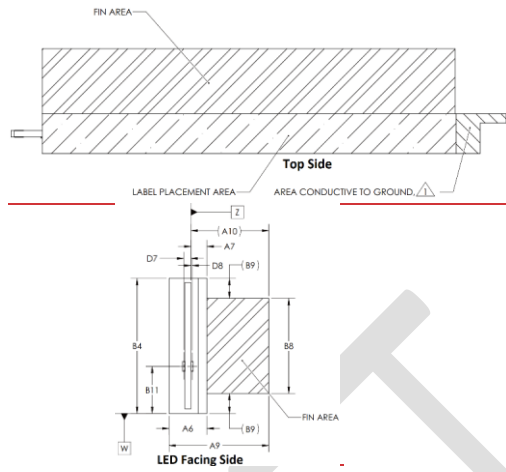
5.5 Physical Definition: 1U Short Form Factor with Optional Asymmetric Enclosure

Unless specified in Table 5-45-4 Table 5-4, Dimensions are the same as in Table 5-35-3 Table 5-3. There are two thicknesses denoted in Table 5-45-4 Table 5-4. The PCB excluding the card edge shall not extend past the defined enclosure area. The device defined in the following section supports either the 1C or 2C card edge as defined in SFF-TA-1002. The area conductive to ground may be larger than what is documented. Labels shall be placed in the label placement area. Security labels are permitted on any surface of the enclosure.





1
2
3
4
5



1

2

3

4

5

6

Notes:

- 1. Host should make grounding contact to at least 1 of these surfaces on the LED facing side.

Figure 5-45-4. 1U Short Form Factor drawing with Optional Asymmetric Enclosure

1 **5.5.1 1U Short Form Factor with Optional Asymmetric Enclosure**2 **Table 5-45-4. 1U Short Form Factor – Optional Asymmetric Enclosure Dimensions**

Dimensions	Millimeters	Tolerance	Comment
A9a	25	+0.35/-0.60	Device Thickness including thick enclosure (25 mm)
A10a	19.46	REF	PCB to outer thickness with Heatsink (25 mm)
A9b	15	+0.35/-0.60	Device Thickness including thick enclosure (15 mm)
A10b	9.46	REF	PCB to outer thickness with Heatsink (15 mm)

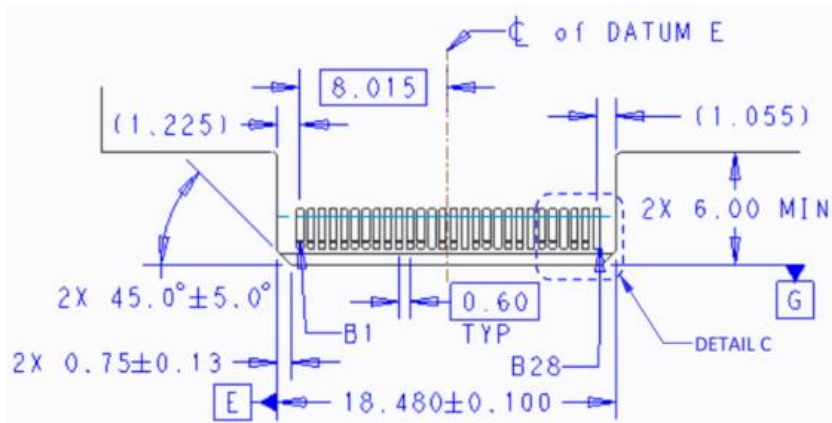
3

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6. Informative: SFF-TA-1002 edge (plug) Mechanical drawing

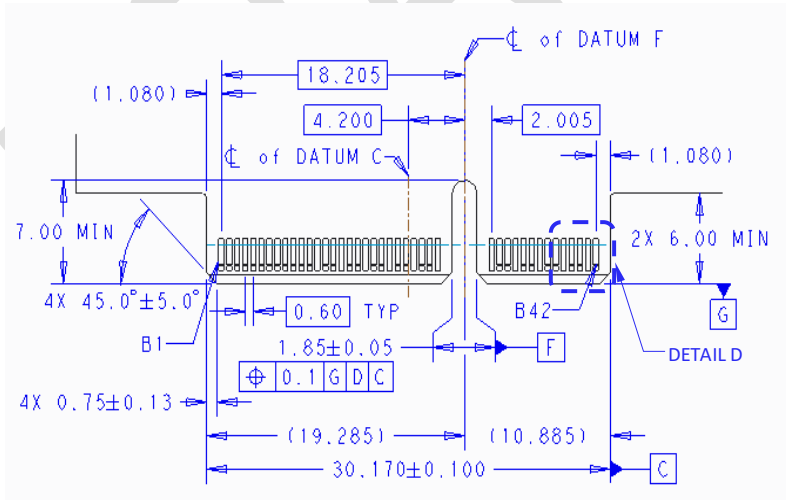
6.1 Overview

This section shows the card edge mechanical drawing for convenience only. See SFF-TA-1002 for normative and performance requirements.



Note: Position A1 on opposite side of card of B1

Figure 6-16-1. 1C (x4) Mating Card Dimensions



Note: Position A1 on opposite side of card of B1

Figure 6-26-2. 2C (x8) Mating Card Dimensions

7. E1.S Power/Thermal Requirements

The following section covers the power and thermal requirements of the device.

7.1 Power

[Table 7-1](#) defines the initial slot power limit for the device. For more details about this and other power requirements, refer to SFF-TA-1009 *Enterprise and Datacenter Standard Form Factor Pin and Signal Specification*.

Table 7-1. Power Requirements for a 1U short (E1.S) system implementation

Parameter	E1.S (5.9/8.01 mm PCB)	E1.S (with 9.5/15/25 mm enclosure)	Comment
Initial Slot Power Limit (12V/pin)	12 W	25 W	Refer to SFF-TA-1009 for definition

7.2 Thermals

For detailed device thermal requirements, refer to SFF-TA-1023 *Thermal Specification for EDSFF Devices*.

7.3 Informative: Recommended Max Power

[Table 7-2](#) defines the recommended maximum sustained power allowed by each device variation.

Table 7-2. Maximum Form Factor Power

Device	E1.S (5.9 mm PCB)	E1.S (8.01 mm PCB)	E1.S (9.5 mm enclosure)	E1.S (15, 25 mm enclosure)	Comment
Max Power	12 W	16 W	20 W	25 W	

7. Informative: System Thermal Design Guidelines

7.1 Overview

The following thermal guidelines are provided to assist in the storage subsystem implementation of the EDSFF 1U short form factor specification. An example implementation is shown in Figure 7-1. In this example, there are 24 add-in cards with 2 different thicknesses connected to a midplane with fans pulling air across the add-in cards. Each add-in card plugs into a connector that is mounted onto the midplane.

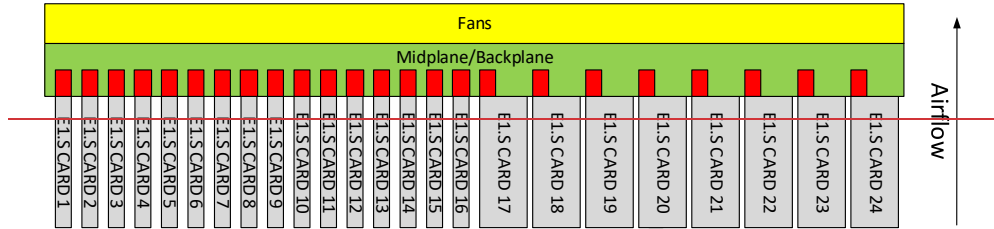


Figure 7-1. Example implementation of 1U short add in cards in an enclosure (Top View)

There are 5 thickness considered for 1U short add in cards: bare PCB at 5.9mm thickness, bare PCB with optional heat spreader at 8.01mm thickness, a fully enclosed device at 9.5mm thickness, a fully enclosed device at 15mm thickness, and a fully enclosed device at 25mm thickness. The heat spreader makes it easier for a system provider to have a common surface such that a heat sink can be attached for additional thermal dissipation. The fully enclosed drives are for a higher operating thermal envelope among other things. As a reference, the connector can support up to a 70W device. To prevent the add in cards from throttling or overheating, system guidelines for both with and without heat spreader add in cards are provided in Table 7-1.

Table 7-1. Thermal guidelines for a 1U short system implementation

Enclosure Parameter	5.9mm-Device	Device-with-Heat-Spreader-(8.01mm)	Device-with-Symmetric-Enclosure-(9.5mm)	Device-with-Asymmetric-Enclosure-(15mm)	Device-with-Asymmetric-Enclosure-(25mm)
Recommended-sustained-power (W)	12	16	20	20	25
Touch-point Temperature-limit (°C)	80	80	80	80	80
Enclosure-Max-Inlet-air-temperature, < 950 m (°C)	35	35	35	35	35
Enclosure-Max-Inlet-air-temperature, 950 m to 3050 m (°C)	35-(1° C for 175 m of elevation gain)	35-(1° C for 175 m of elevation gain)	35-(1° C for 175 m of elevation gain)	35-(1° C for 175 m of elevation gain)	35-(1° C for 175 m of elevation gain)
Add-in-card-to-add-in-card-pitch (mm)	9	11	13	17	26
Recommended-Fan-Pressure-loss-across-device (Pascal)	83	52	64	40	21
Airflow, average min-per-device (CFM). 1 CFM = 1.7 m³/h	1.41-(0.01 CFM for every 1° C below 35° C inlet temp)	1.71-(0.06 CFM for every 1° C below 35° C inlet temp)	2.02-(0.02 CFM for every 1° C below 35° C inlet temp)	1.5-(0.02 CFM for every 1° C below 35° C inlet temp)	4.10-(0.04 CFM for every 1° C below 35° C inlet temp)